

Small Signal Product

200mW High Speed SMD Switching Diode

FEATURES

- Fast switching device ($t_{rr} < 4.0\text{ns}$)
- Surface Mount Device Type
- Moisture sensitivity level 1
- Matte Tin (Sn) lead finish with Nickel (Ni) underplate
- Pb free version and RoHS compliant
- Packing code with suffix "G" means green compound (halogen-free)


SOD-323F


MECHANICAL DATA

- Case: Flat lead SOD-323F small outline plastic package
- Terminal: Matte tin plated, lead free, solderable per MIL-STD-202, Method 208 guaranteed
- High temperature soldering guaranteed: 260°C/10s
- Polarity: Indicated by cathode band
- Weight: $6 \pm 0.5\text{mg}$
- Marking code: S4



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)			
PARAMETER	SYMBOL	VALUE	UNIT
Power Dissipation	P_D	200	mW
Repetitive Peak Reverse Voltage	V_{RRM}	90	V
Reverse Voltage	V_R	80	V
Minimum Breakdown Voltage at $I_R = 100\mu\text{A}$	V_{BR}	80	V
Forward Current	I_F	250	mA
Continue Forward Current	I_O	150	mA
Repetitive Peak Forward Voltage	I_{FSM}	500	mA
Maximum Reverse Leakage Current at $V_R = 80\text{V}$	I_R	100	nA
Maximum Forward Voltage at $I_F = 100\text{mA}$	V_F	1.2	V
Maximum Reverse Recovery Time at $I_F = 10\text{mA}$, $V_R = 6\text{V}$, $R_L = 100\text{ Ohms}$	t_{rr}	4	ns
Maximum Junction Capacitance at $V_R = 0.5\text{V}$, $f = 1\text{MHz}$	C_j	4	pF
Operating Temperature Range	T_{OPR}	- 65 to +150	$^\circ\text{C}$
Storage Temperature Range	T_{STG}	- 65 to +150	$^\circ\text{C}$

Note : These ratings are limiting values above which the serviceability of the diode may be impaired

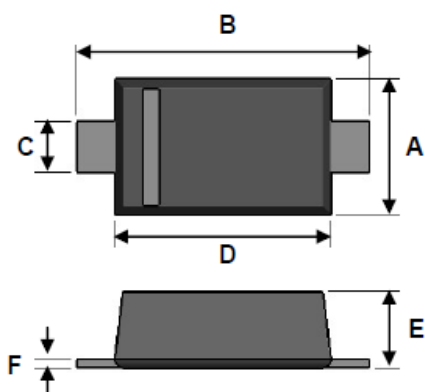
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ORDERING INFORMATION					
PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING
1SS355	-xx (Note 1)	RR	G	SOD-323F	3K / 7" Reel
		R9			10K / 13" Reel

Note 1: Part No. Suffix „-xx “ would be used for special requirement

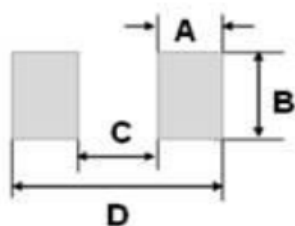
EXAMPLE					
PREFERRED P/N	PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION
1SS355 RRG	1SS355		RR	G	Multiple manufacture source Green compound
1SS355-L0 RRG	1SS355	-L0	RR	G	Defined manufacture source Green compound
1SS355-B0 RRG	1SS355	-B0	RR	G	Defined manufacture source Green compound

PACKAGE OUTLINE DIMENSIONS
SOD-323F



DIM.	Unit (mm)		Unit (inch)	
	Min	Max	Min	Max
A	1.15	1.35	0.045	0.053
B	2.30	2.80	0.091	0.110
C	0.25	0.40	0.010	0.016
D	1.60	1.80	0.063	0.071
E	0.80	1.10	0.031	0.043
F	0.05	0.25	0.002	0.010

SUGGEST PAD LAYOUT



DIM.	Unit (mm)	Unit (inch)
	Typ.	Typ.
A	0.630	0.025
B	0.830	0.033
C	1.600	0.063
D	2.860	0.113

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